

■ Features

- 0.30 Inch Single Digit Display
- Long lifetime operation
- IC compatible
- Low power dissipation
- Gray surface & white segment or dot
- RoHS compliant

■ Applications

- Counting device
- Clock

■ Photo



■ Absolute Maximum Rating (Ta=25°C)

Item	Symbol	Value		Unit
		W/B/TG	YG/Y/O/R/RA	
DC Forward Current	I _F	25	25	mA
Pulse Forward Current#	I _{FP}	80	80	mA
Reverse Voltage	V _R	5	5	V
Power Dissipation	P _t	90	65	mW
Operating Temperature	T _{opr}	-30~ +85		°C
Storage Temperature	T _{stg}	-40~ +100		°C
Lead Soldering Temperature(1.6mm Below body)	T _{sol}	260°C/3sec		°C

#Pulse width Max.10ms Duty ratio max 1/10

*Reflow time Max3seconds

■ Electrical -Optical Characteristics (Ta=25°C)

Part Number	Color			V _F (V)			I _R (μA)	I _v (mcd)			λD(nm)		
				Min.	Typ.	Max.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
				I _F =20mA			V _R =5V	I _F =10mA			I _F =20mA		
OSK1030A-IW(LW)	White	W		-	3.1	3.6	100	20	50	80	6000K	8000K	10000K
OSK1030A-IB(LB)	Blue	B		-	3.1	3.6	100	5	10	15	465	470	475
OSK1030A-IG(LG)	True Green	TG		-	3.1	3.6	100	8	15	25	510	520	530
OSK1030A-IYG(LYG)	Yellow Green	YG		-	2.1	2.6	100	3	9	15	565	570	575
OSK1030A-IY(LY)	Yellow	Y		-	2.1	2.6	100	5	10	15	585	590	595
OSK1030A-IO(LO)	Orange	O		-	2.1	2.6	100	5	10	15	600	605	610
OSK1030A-IR(LR)	Red	R		-	2.1	2.6	100	5	10	15	625	630	640
OSK1030A-IRA(LRA)	High Red	RA		-	2.1	2.6	100	15	20	25	620	625	630

*1 Tolerance of measurements of color temperature is ±10%

*2 Tolerance of measurements of dominant wavelength is ±1nm

*3 Tolerance of measurements of luminous intensity is ±15%

*4 Tolerance of measurements of forward voltage is ±0.1V

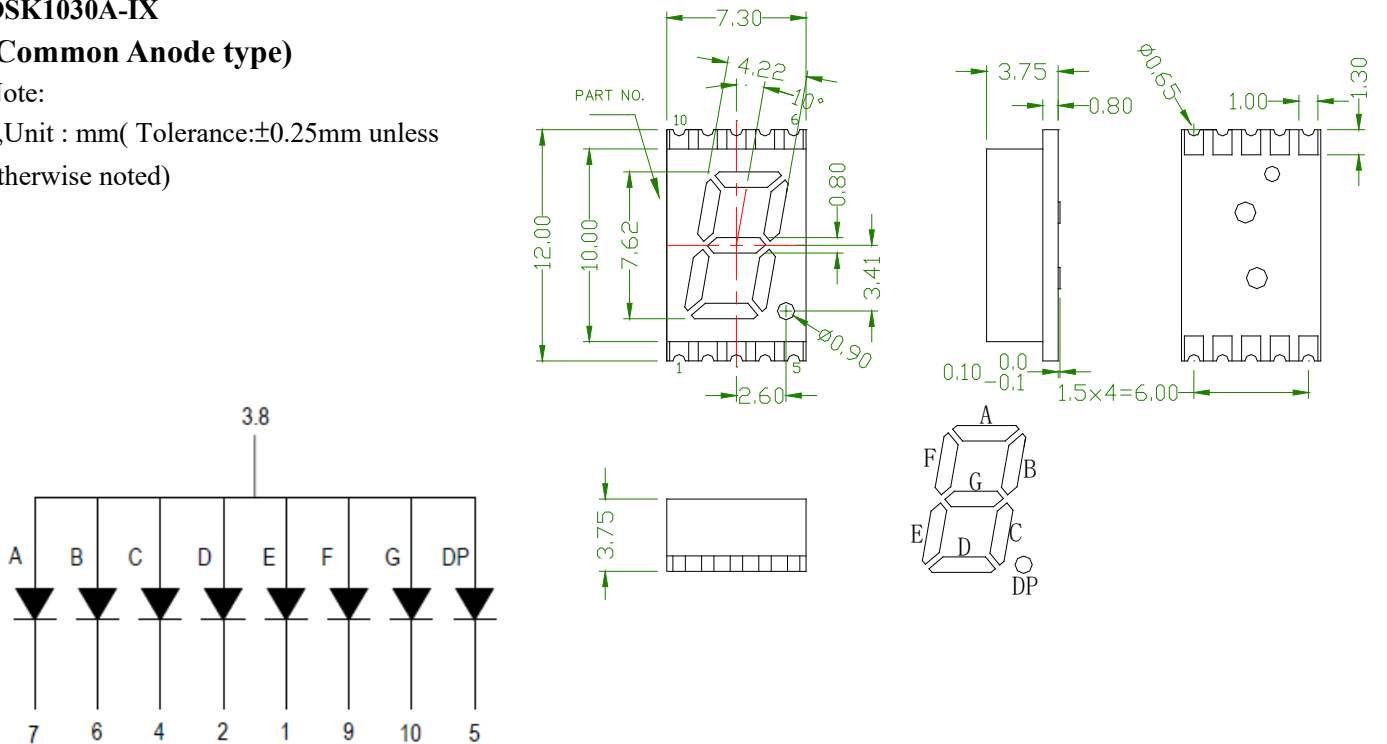
■ Package Dimensions

OSK1030A-IX

(Common Anode type)

Note:

1, Unit : mm (Tolerance: ± 0.25 mm unless otherwise noted)

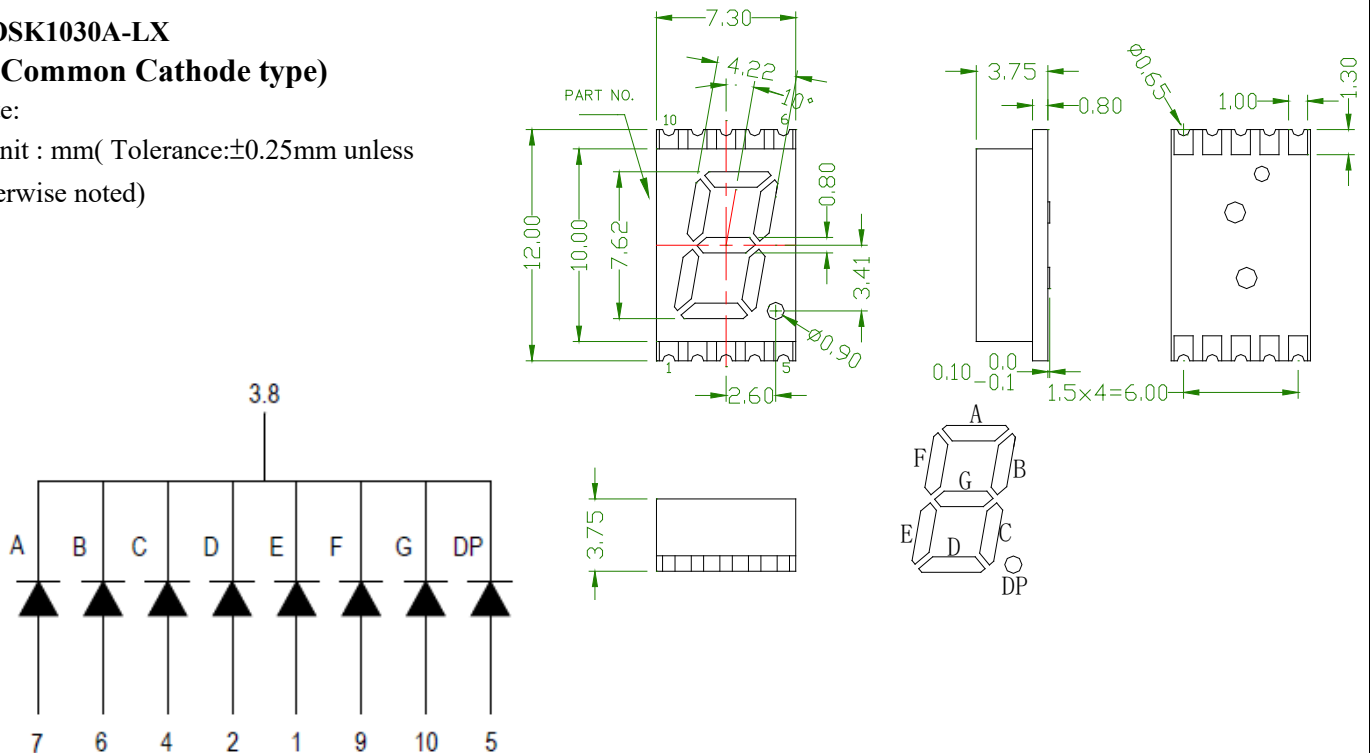


OSK1030A-LX

(Common Cathode type)

Note:

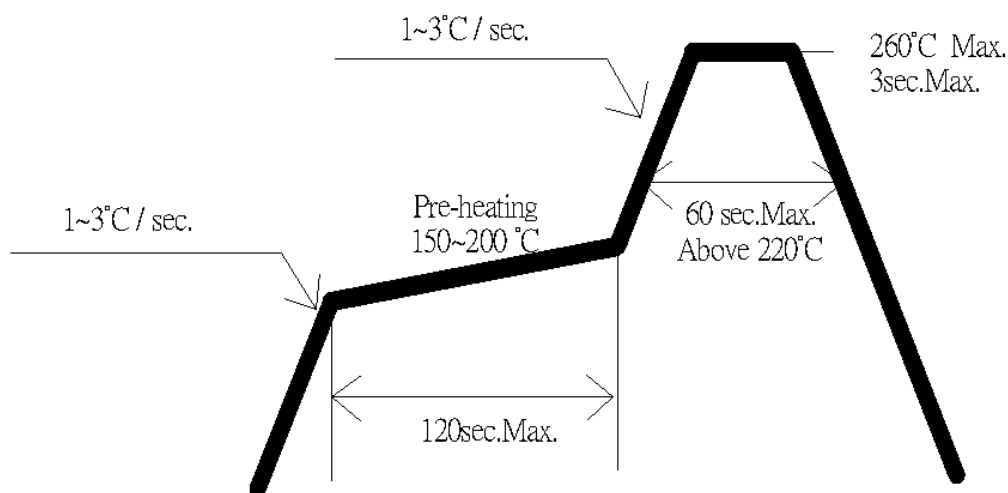
1, Unit : mm (Tolerance: ± 0.25 mm unless otherwise noted)



■ Soldering Conditions

Reflow Soldering		Hand Soldering	
Pre-Heat	150 ~ 200°C	Temperature Soldering time	350°C Max. 3 sec. Max. (one time only)
Pre-Heat Time	120 sec. Max.		
Peak Temperature	260°C Max.		
Dipping Time	3 sec. Max.		
Condition	Refer to Temperature-profile		

• Reflow Soldering Condition(Lead-free Solder)



*Recommended soldering conditions vary according to the type of LED

*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.

*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.

• All SMD LED products are pb-free soldering available.

• Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.

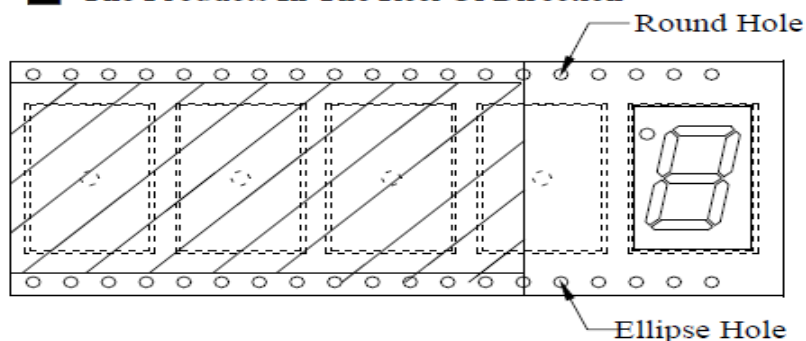
• Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

• Reflow soldering should not be done more than two times.

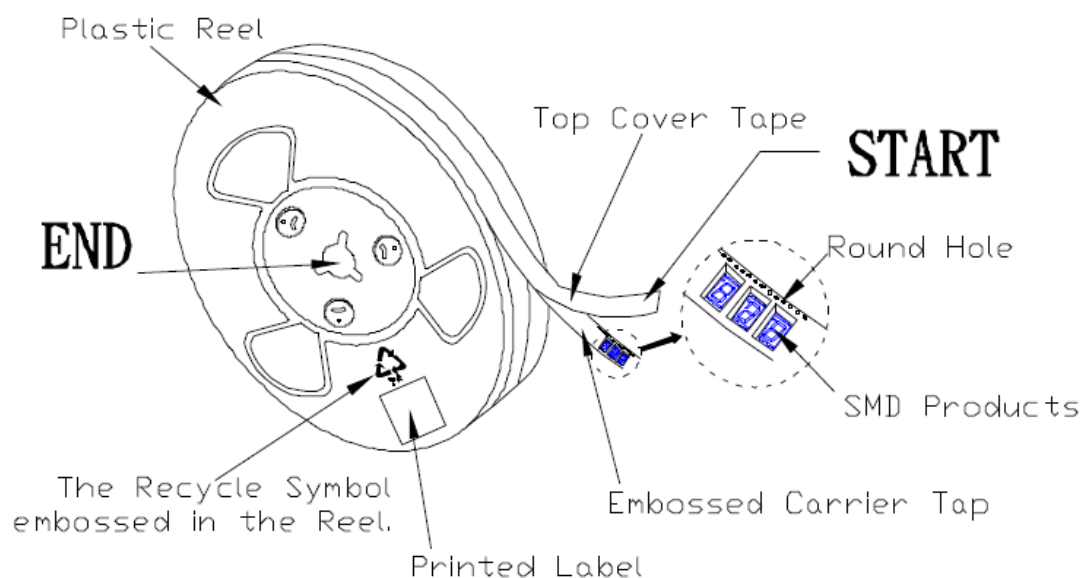
• When soldering, do not put stress on the LEDs during heating.

• After soldering, do not warp the circuit board.

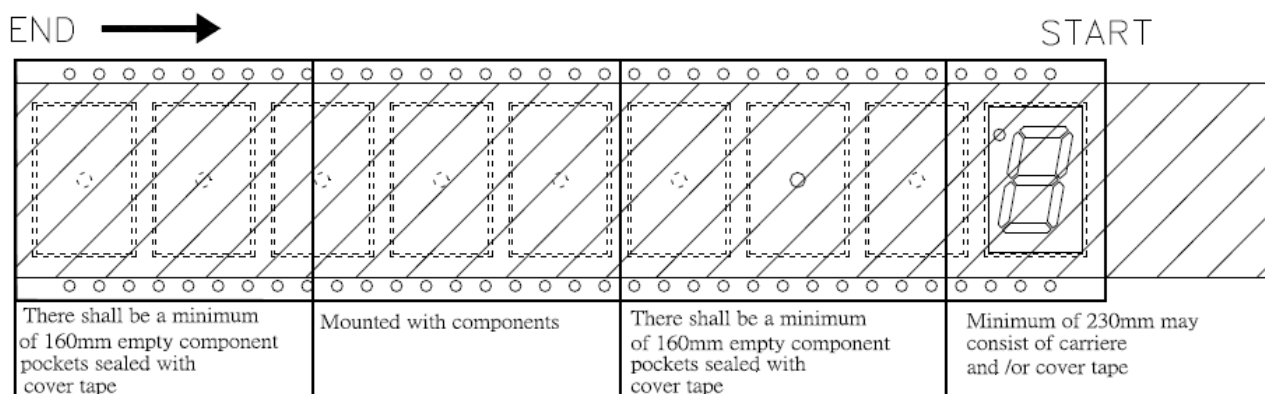
■ The Products In The Reel Of Direction



■ Label Direction & Content In The Roll



■ USER FEED DIRECTION



■ Package Criteria:

1. Total unit per reel is 1000PCS.
Max 5 reels/5000PCS are packaged in each carton



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

LEVEL

3

1. Calculated shelf life in sealed bag: 12 months at $<40^{\circ}\text{C}$ and $<90\%$ relative humidity (RH).
2. Peak package body temperature: Per Product Label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
 - a) Mounted within: 168 hours of factory conditions $\leq 30^{\circ}\text{C}/60\%\text{RH}$
 - b) stored per J-STD-033
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card is $>10\%$ when read at $23 \pm 5^{\circ}\text{C}$
 - b) 3a or 3b not met.
5. If baking is required, devices may be baked for 20 hours at $60 \pm 5^{\circ}\text{C}$

Bag Seal Date: _____

If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020